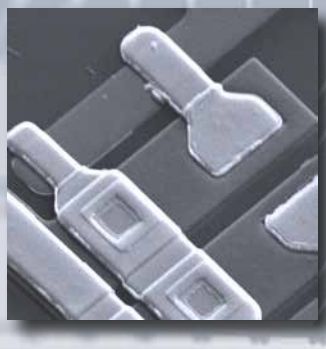
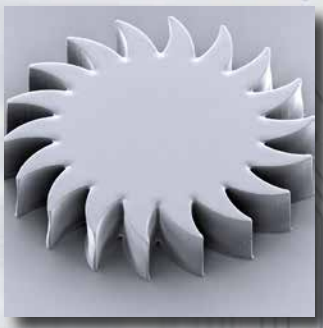
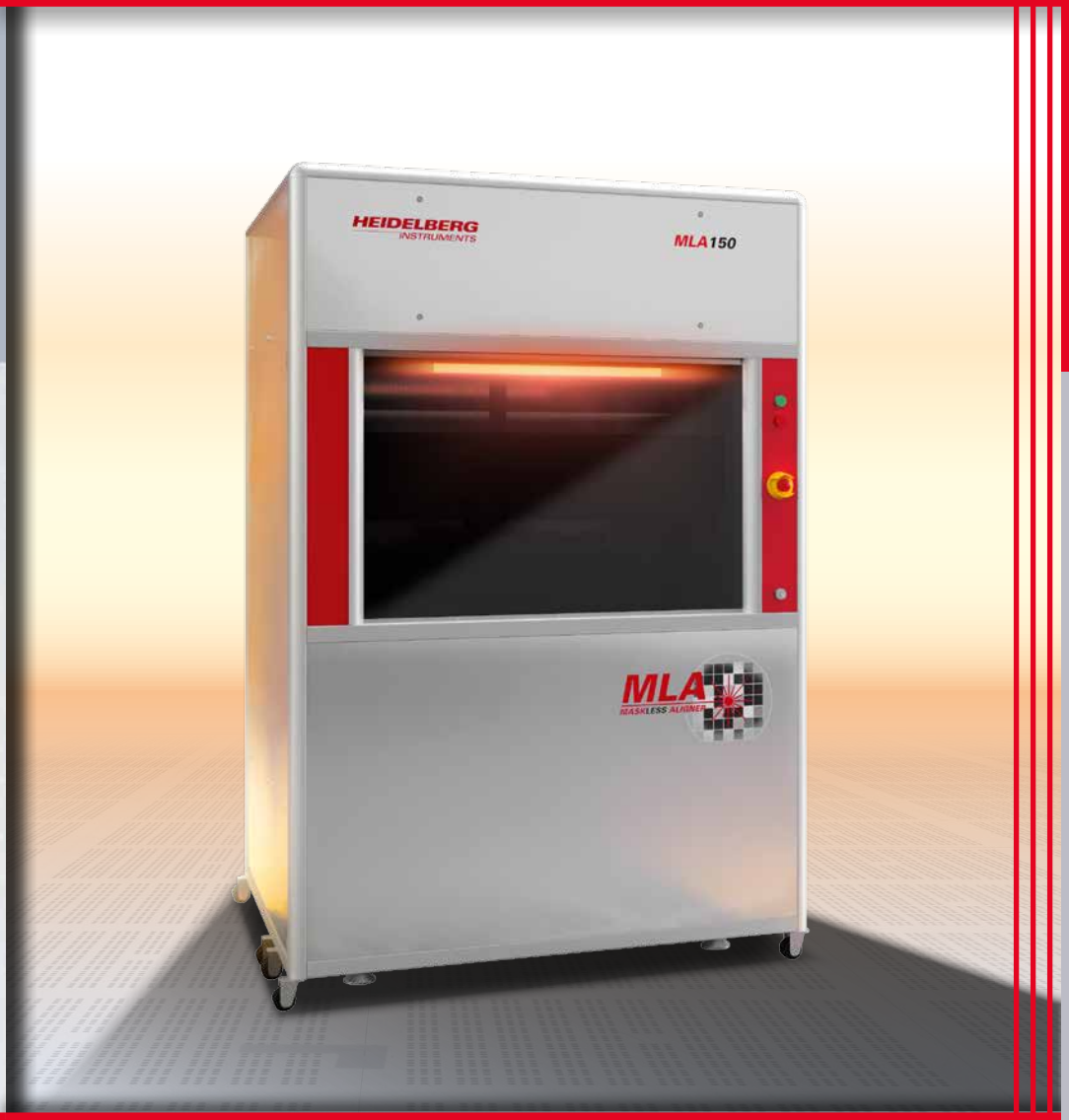
HEIDELBERG
INSTRUMENTS

pioneers in photolithography







MLA150

Maskless Aligner

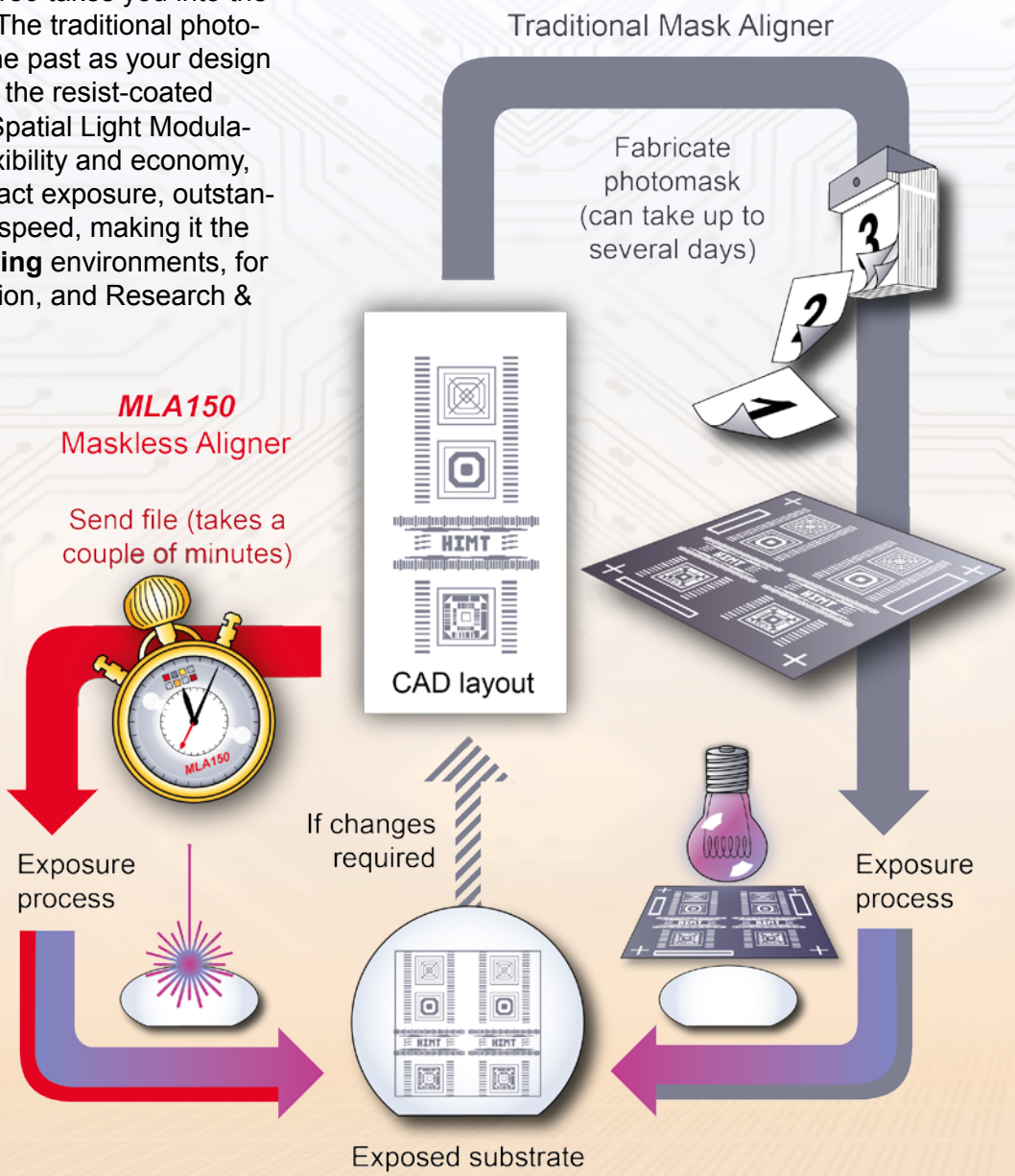
MLA
MASKLESS ALIGNER

GO MASKLESS
ACHIEVE MORE

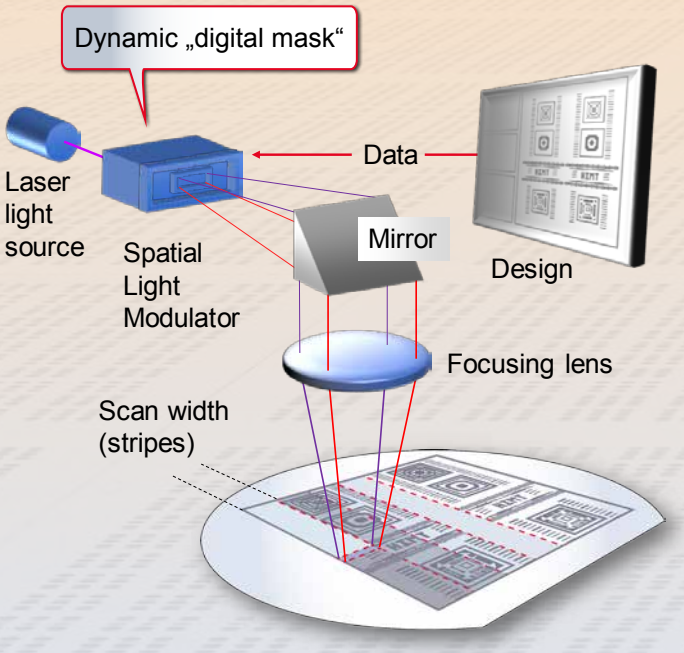
The Maskless Aligner *MLA150* and the maskless photolithography cycle

The Maskless Aligner MLA150 takes you into the future of photolithography: The traditional photomask becomes a thing of the past as your design file is exposed directly onto the resist-coated wafer via a 2-dimensional Spatial Light Modulator (SLM). In addition to flexibility and economy, MLA150 provides non-contact exposure, outstanding ease of use, and high speed, making it the ideal tool in **rapid prototyping** environments, for low- to mid-volume production, and Research & Development.

The Maskless Aligner was first introduced in 2015. Since then, the revolutionary, state-of-the-art maskless technology has become firmly established. Today, the MLA150 serves as a trusted, indispensable workhorse in many multi-user facilities, nanofabrication labs, and national institutes.



Application areas: MEMS, micro-optics, diffractive optical elements, sensors, electronic components and many more



Speed

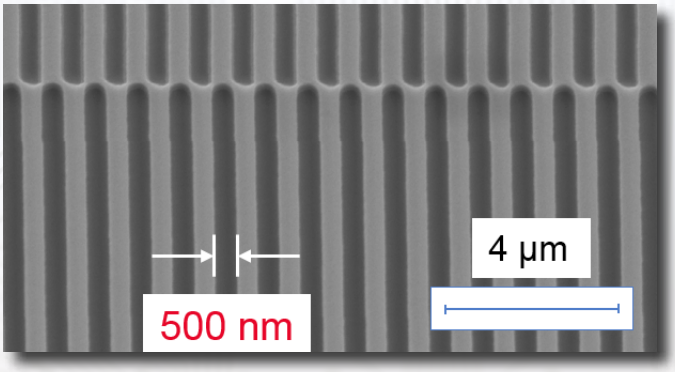
- High-speed Spatial Light Modulator
- Bidirectional writing process
- „Empty stripes“ optimization

MLA150 exposure times*

Laser wavelength	405 nm
50 x 50 mm²	4 minutes
100 x 100 mm²	9 minutes
150 x 150 mm²	16 minutes
200 x 200 mm²	36 minutes

* for exposure at 100 mJ/cm² and minimum feature size of 1 µm

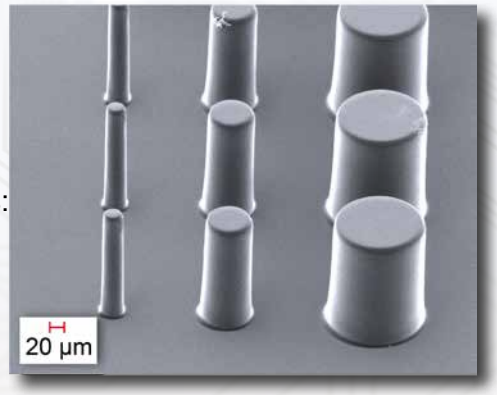
High resolution



High resolution mode: Vertical 500 nm lines and spaces. Resist: S1805. Wavelength: 375 nm

High-aspect-ratio microstructures

- Adjustable depth of focus
- Aspect ratio up to 1:20
- Applications: Micro-fluidics, MEMS, wave-guides



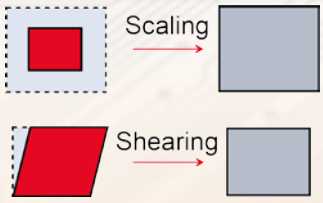
High aspect ratio: Pillars. Resist: 160 µm SU-8

Fast and high-precision alignment

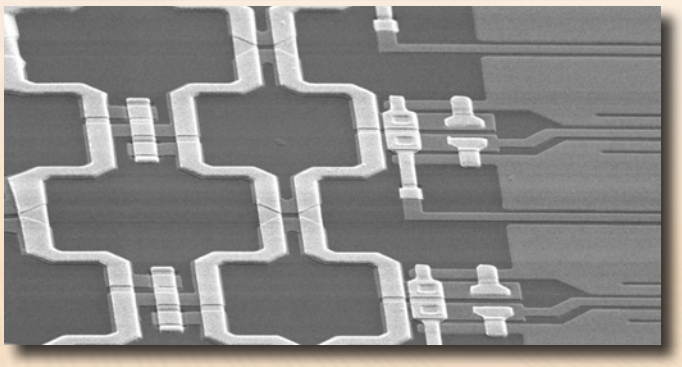
- Global and field-by-field alignment
- Backside alignment
- Alignment accuracy of better than 500 nm
- Fast and easy alignment procedure

To view the procedure, watch our movie *„Photolithography without a mask: Multilayer lithography with the Maskless Aligner MLA150“* on http://movies.himt.de

- Alignment error compensation: Corrects for rotation, offset, scaling and shearing



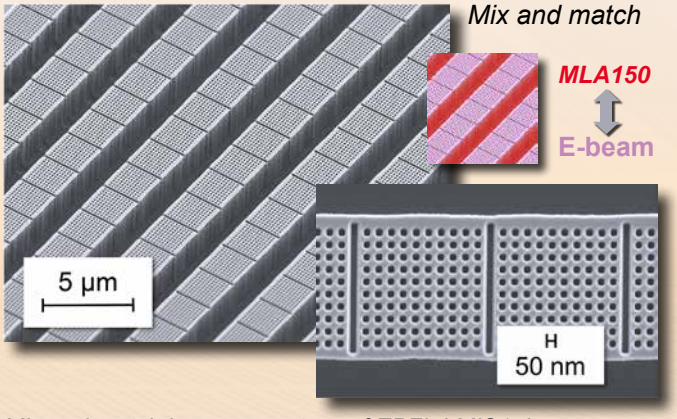
- Allows mix and match between different tool sets, e.g. e-beam or thermal scanning probe lithography and laser lithography



SQUID magnetic flux sensor; 18 layer process

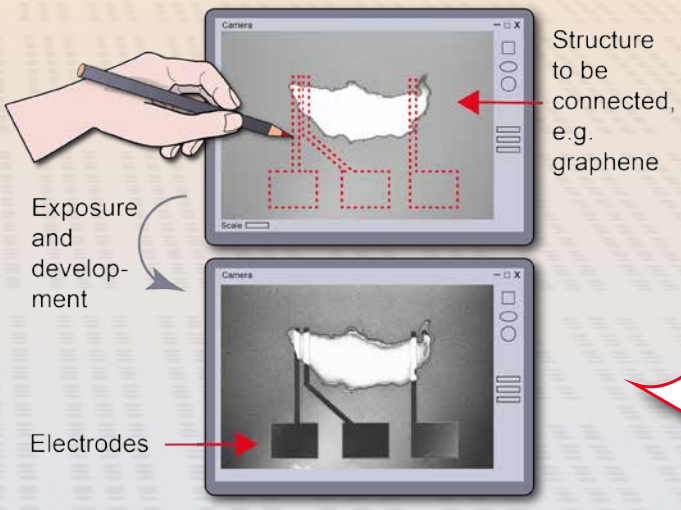
Courtesy of the Kirchhoff Institute for Physics, Heidelberg

Mix and match



Mix and match images courtesy of EPFL LMIS1, Lausanne

Flexibility



- The available solid state laser sources (405 and 375 nm) make the system compatible with all broadband UV photoresists (including SU-8) and can both be installed in the MLA150 at the same time
- 3D-patterning with grayscale lithography
- Optional: exchangeable chucks with individual vacuum layouts

The Draw Mode: Add individual features to a previously patterned substrate. Using graphic elements, or even a bitmap, simply „draw“ the desired structures - such as labels, markers, or electrical connections - directly into the camera image.

MLA150 system specifications

	Write Mode I *	Write Mode II *
Writing performance		
Minimum structure size [µm]	0.6	1
Linewidth variation [3σ, nm]	100	120
Global 2nd layer alignment [3σ, nm]	500	500
Local 2nd layer alignment [3σ, nm]	250	250
Backside alignment [3σ, nm]	1000	1000
Exposure time 405 nm laser for 4“ wafer [min]	35	9
Exposure time 375 nm laser for 4“ wafer [min]	35	20
Max. write speed 405 nm laser [mm²/min]	285	1100
Max. write speed 375 nm laser [mm²/min]	285	500
System features		
Light source	Diode lasers: 8 W at 405 nm, 2.8 W at 375 nm, or both	
Substrate sizes	Variable: 3 x 3 mm² to 6” x 6” | Optional: 8” x 8” | Customizable on request	
Substrate thickness	0 - 12 mm	
Maximum exposure area	150 x 150 mm²; optional: 200 x 200 mm²	
Temperature controlled flow box	Temperature stability ± 0.1°	
Real-time autofocus	Air-gauge or optical	
Autofocus compensation range	180 µm	
Grayscale	128 gray levels	
Software features	Exposure wizard, resist database, automatic labeling and serialization, Draw Mode for CADless exposures, Substrate tracking / history	
System dimensions (lithography unit)		
Height × width × depth	1950 mm × 1300 mm × 1300 mm	
Weight	1100 kg	
Installation requirements		
Electrical	230 VAC ± 5%, 50/60 Hz, 16 A	
Compressed air	6 - 10 bar, stability ± 0.5 bar	
Economical considerations		
Saves on the cost of photomasks		
Low running costs for maintenance, energy consumption, spare parts		
Solid state laser light sources with lifetime of several years		

* Please note that only one write mode can be installed on the system

Please note: Specifications depend on individual process conditions and may vary according to equipment configuration. Write speed depends on exposure area. Design and specifications are subject to change without prior notice.

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